

Amend the application identified as follows:

**IN THE CLAIMS**

Amend claims 1-3 as follows:

- sub 1*
1. (Once Amended) A semiconductor integrated circuit device comprising:
- a die connected to a ground lead and a power lead;
  - a ground plane connected to the ground lead;
  - an electrically insulating layer between said die and said ground plane;
  - a decoupling capacitor having a first end and a second end, the first end connected to the ground lead and the second end connected to the power lead; and
  - an encapsulating material for encapsulating the die, the ground plane, the electrically insulating layer and the decoupling capacitor.
- sub 2*
2. (Once Amended) The semiconductor integrated circuit device according to Claim 1, wherein said ground plane is adjacent a first plane of a printed circuit board for mounting electronic parts.
3. (Once Amended) The semiconductor integrated circuit device according to Claim 2, wherein said ground plane extends in two dimensions beyond the edges of said die.

Add the following new claim:

- sub 3*
11. The semiconductor integrated circuit device according to Claim 1, wherein the electrically insulating layer comprises one of air, encapsulating material or bonding material.